IN THE CLAIMS

Please cancel claims 3 and 10 without prejudice.

Please amend the following claims which are pending in the present application:

1. (Currently amended) An electronic assembly, comprising:

a carrier substrate having an upper plane;

a die having a die substrate and an integrated circuit formed on one side of the die substrate, the die having a lower major surface over the upper plane, an upper major surface, and a plurality of side edge surfaces from the upper major surface to the lower major surface, a corner edge portion where extensions of two of the side edge surfaces meet, having been removed such that the die is rounded at the corner edge portion; and

a solidified underfill material between and contacting both the upper plane of the carrier substrate and the lower surface of the die.

2. (Original) The electronic assembly of claim 1, wherein the corner edge portion has an area of between 537 μm^2 and 860000 μm^2.

3. (Cancelled)

4. (Currently amended) The electronic assembly of claim [[3]] 1, wherein the die has a radius of between 50 μm and 1000 μm at the corner edge portion.

5. (Currently amended) The electronic assembly of claim [[3]] 1, wherein an entire thickness of the die from the upper to the lower major surface is rounded.

6. (Original) The electronic assembly of claim 1, wherein the underfill material has a different CTE than the substrate.

7. (Original) The electronic assembly of claim 1, further comprising:

a plurality of conductive interconnection members between and electrically connecting the carrier substrate to the die, the underfill material being disposed between the conductive interconnection members.

8. (Currently amended) An electronic component, comprising:

a die having a die substrate and an integrated circuit formed on the die substrate, the die having upper and lower major surfaces and a plurality of side edge surfaces from the upper to the lower major surface, a corner edge portion where extensions of two of the side edge surfaces meet, having been removed such that the die is rounded at the corner edge portion.

9. (Original) The electronic component of claim 8, wherein the corner edge portion has an area of between 537 μm^2 and 860000 μm^2.

10. (Cancelled)

11. (Currently amended) The electronic component of claim [[10]] 8, wherein the die has a radius of between 50 μm and 1000 μm at the corner edge portion.

12. (Currently amended) The electronic component of claim [[10]] 8, wherein an entire thickness of the die from the upper to the lower major surface is rounded.

13. (Original) The electronic component of claim 8, further comprising:

a plurality of conductive interconnection members on a side of the die of the integrated circuit.

14. (Original) The electronic component of claim 13, wherein the conductive interconnection members are solder balls.

15-20. (Cancelled)